

SN54136, SN54LS136, SN74136, SN74LS136 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES WITH OPEN-COLLECTOR OUTPUTS

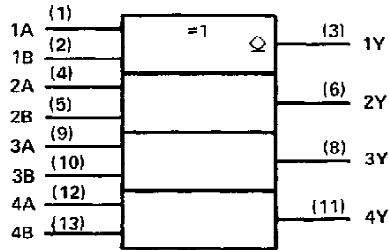
DECEMBER 1972 - REVISED MARCH 1988

FUNCTION TABLE

| INPUTS | | OUTPUT |
|--------|---|--------|
| A | B | Y |
| L | L | L |
| L | H | H |
| H | L | H |
| H | H | L |

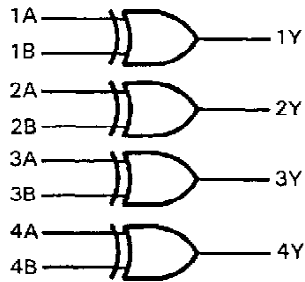
H = high level, L = low level

logic symbol†



†This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

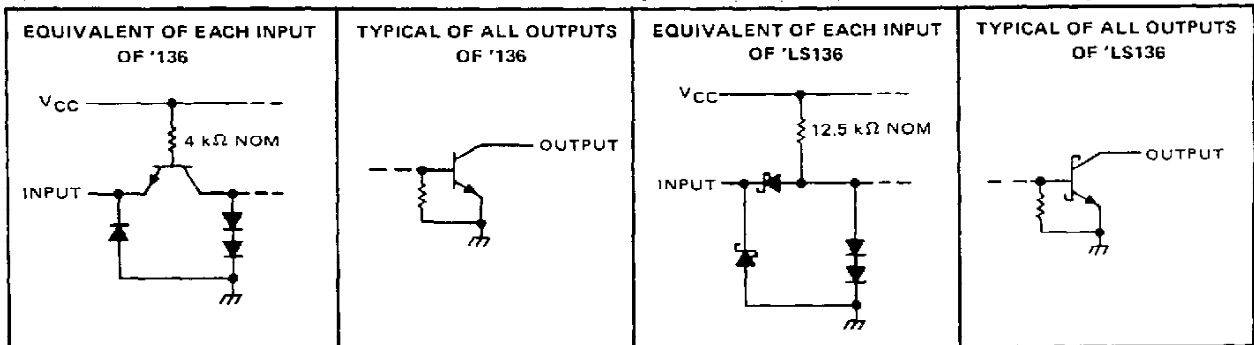
logic diagram (each gate)



positive logic

$$Y = A \oplus B = \bar{A} \cdot B + A \cdot \bar{B}$$

schematics of inputs and outputs



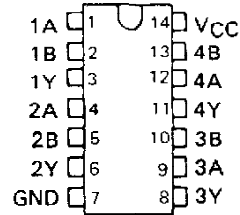
Resistor values shown are nominal.

SN54136, SN54LS136 . . . J OR W PACKAGE

SN74136 . . . N PACKAGE

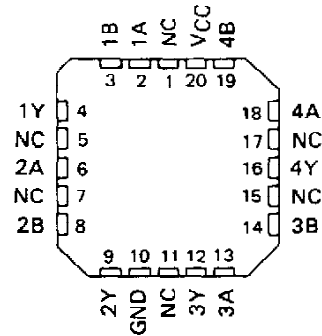
SN74LS136 . . . D OR N PACKAGE

(TOP VIEW)



SN54LS136 . . . FK PACKAGE

(TOP VIEW)



NC - No internal connection

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SN54136, SN74136 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES WITH OPEN-COLLECTOR OUTPUTS

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

| | |
|---|----------------|
| Supply voltage, V_{CC} (see Note 1) | 7 V |
| Input voltage | 5.5 V |
| Operating free-air temperature range: SN54136 | -55°C to 125°C |
| SN74136 | 0°C to 70°C |
| Storage temperature range | -65°C to 150°C |

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

| | SN54136 | | | SN74136 | | | UNIT |
|---------------------------------------|---------|-----|-----|---------|-----|------|------|
| | MIN | NOM | MAX | MIN | NOM | MAX | |
| Supply voltage, V_{CC} | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| High-level input voltage, V_{IH} | 2 | | | 2 | | | V |
| Low-level input voltage, V_{IL} | | | 0.8 | | | 0.8 | V |
| High-level output voltage, V_{OH} | | | 5.5 | | | 5.5 | V |
| Low-level output current, I_{OL} | | | 16 | | | 16 | mA |
| Operating free-air temperature, T_A | -55 | | 125 | 0 | | 70 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS [†] | SN54136 | | | SN74136 | | | UNIT | |
|-----------|--|---------|------------------|------|---------|------------------|------|---------------|----|
| | | MIN | TYP [‡] | MAX | MIN | TYP [‡] | MAX | | |
| V_{IK} | $V_{CC} = \text{MIN}$, $I_I = -8 \text{ mA}$ | | | -1.5 | | | -1.5 | V | |
| I_{OH} | $V_{CC} = \text{MIN}$, $V_{IH} = 2 \text{ V}$, $V_{IL} = 0.8 \text{ V}$, $V_{OH} = 5.5 \text{ V}$ | | | | | | 0.25 | mA | |
| | $V_{CC} = \text{MIN}$, $V_{IH} = 2 \text{ V}$, $V_{IL} = 0.7 \text{ V}$, $V_{OH} = 5.5 \text{ V}$ | | | 0.25 | | | | | |
| V_{OL} | $V_{CC} = \text{MIN}$, $V_{IH} = 2 \text{ V}$, $V_{IL} = 0.8 \text{ V}$, $I_{OL} = 16 \text{ mA}$ | | | 0.2 | 0.4 | | 0.2 | 0.4 | V |
| I_I | $V_{CC} = \text{MAX}$, $V_I = 5.5 \text{ V}$ | | | 1 | | | 1 | mA | |
| I_{IH} | $V_{CC} = \text{MAX}$, $V_I = 2.4 \text{ V}$ | | | 40 | | | 40 | μA | |
| I_{IL} | $V_{CC} = \text{MAX}$, $V_I = 0.4 \text{ V}$ | | | -1.6 | | | -1.6 | mA | |
| I_{CC} | $V_{CC} = \text{MAX}$, See Note 2 | | | 30 | 43 | | 30 | 50 | mA |

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$.

NOTE 2: I_{CC} is measured with one input of each gate at 4.5 V, the other inputs grounded, and the outputs open.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$

| PARAMETER [¶] | FROM (INPUT) | TEST CONDITIONS | | MIN | TYP | MAX | UNIT | |
|------------------------|--------------|------------------|---|-----|-----|-----|------|----|
| | | Other input low | Other input high | | | | | |
| t_{PLH} | A or B | Other input low | $C_L = 15 \text{ pF}$, $R_L = 400 \Omega$, See Note 3 | | | 12 | 18 | ns |
| t_{PHL} | | | | | | 39 | 50 | |
| t_{PLH} | A or B | Other input high | See Note 3 | | | 14 | 22 | ns |
| t_{PHL} | | | | | | 42 | 55 | |

[¶] t_{PLH} propagation delay time, low-to-high-level output

t_{PHL} propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



SN54LS136, SN74LS136

QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES

WITH OPEN-COLLECTOR OUTPUTS

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

| | |
|---|----------------|
| Supply voltage, V_{CC} (see Note 1) | 7 V |
| Input voltage | 7 V |
| Operating free-air temperature range: SN54LS136 | -55°C to 125°C |
| SN74LS136 | 0°C to 70°C |
| Storage temperature range | -65°C to 150°C |

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

| | SN54LS136 | | | SN74LS136 | | | UNIT |
|---------------------------------------|-----------|-----|-----|-----------|-----|------|------|
| | MIN | NOM | MAX | MIN | NOM | MAX | |
| Supply voltage, V_{CC} | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| High-level output voltage, V_{OH} | 5.5 | | | 5.5 | | | V |
| Low-level output current, I_{OL} | 4 | | | 8 | | | mA |
| Operating free-air temperature, T_A | -55 | 125 | | 0 | 70 | | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS† | SN54LS136 | | SN74LS136 | | UNIT | |
|--|--|-------------------------|------|-----------|------|---------------|------|
| | | MIN | TYP‡ | MAX | MIN | | TYP‡ |
| V_{IH} High-level input voltage | | 2 | | 2 | | V | |
| V_{IL} Low-level input voltage | | 0.7 | | 0.8 | | V | |
| V_{IK} Input clamp voltage | $V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$ | -1.5 | | -1.5 | | V | |
| I_{OH} High-level output current | $V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = V_{IL \text{ max}}, V_{OH} = 5.5 \text{ V}$ | 100 | | 100 | | μA | |
| V_{OL} Low-level output voltage | $V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = V_{IL \text{ max}}$ | $I_{OL} = 4 \text{ mA}$ | 0.25 | 0.4 | 0.25 | 0.4 | V |
| | | $I_{OL} = 8 \text{ mA}$ | | | 0.35 | 0.5 | |
| I_I Input current at maximum input voltage | $V_{CC} = \text{MAX}, V_I = 7 \text{ V}$ | 0.2 | | 0.2 | | mA | |
| I_{IH} High-level input current | $V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$ | 40 | | 40 | | μA | |
| I_{IL} Low-level input current | $V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$ | -0.8 | | -0.8 | | mA | |
| I_{CC} Supply current | $V_{CC} = \text{MAX}, \text{ See Note 2}$ | 6.1 | 10 | 6.1 | 10 | mA | |

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

NOTE 2: I_{CC} is measured with one input of each gate at 4.5 V, the other inputs grounded, and the outputs open.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$

| PARAMETER ¹ | FROM (INPUT) | TEST CONDITIONS | | MIN | TYP | MAX | UNIT |
|------------------------|--------------|------------------|---|-----|-----|-----|------|
| | | | | | | | |
| t_{PLH} | A or B | Other input low | $C_L = 15 \text{ pF}, R_L = 2 \text{ k}\Omega,$ (See Note 3) | 18 | 30 | ns | |
| t_{PHL} | | | | 18 | 30 | | |
| t_{PLH} | A or B | Other input high | (See Note 3) | 18 | 30 | ns | |
| t_{PHL} | | | | 18 | 30 | | |

¹ t_{PLH} propagation delay time, low-to-high-level output

t_{PHL} propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|----------------------------|-------------------------|----------------------|--------------|------------------------------------|-------------------------|
| 5962-9231901MCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9231901MC A SNJ54LS136J | Samples |
| SN54LS136J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | SN54LS136J | Samples |
| SN74136N | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI | 0 to 70 | | |
| SN74LS136D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS136 | Samples |
| SN74LS136DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS136 | Samples |
| SN74LS136DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS136 | Samples |
| SN74LS136DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS136 | Samples |
| SN74LS136N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | SN74LS136N | Samples |
| SN74LS136N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI | 0 to 70 | | |
| SN74LS136NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | SN74LS136N | Samples |
| SN74LS136NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 74LS136 | Samples |
| SN74LS136NSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 74LS136 | Samples |
| SNJ54LS136J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9231901MC A SNJ54LS136J | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS136, SN74LS136 :

● Catalog: [SN74LS136](#)

● Military: [SN54LS136](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LS136DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74LS136NSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LS136DR | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| SN74LS136NSR | SO | NS | 14 | 2000 | 367.0 | 367.0 | 38.0 |

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211283-3/E 08/12



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.

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